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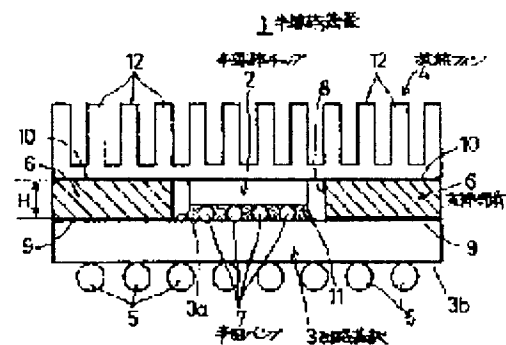
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(54) SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor device in which radiation efficiency is improved while maintaining preferable electrical connection between a semiconductor chip and a circuit board by supporting a radiating fin thermally joined to the semiconductor chip with a supporting member having the same height as that of the semiconductor chip from a mounting face of a substrate in a position around the semiconductor chip mounting position on the substrate.

SOLUTION: A supporting member 6 is made of glass epoxy resin and is constructed so that a semiconductor chip 2 mounted on a circuit board 3 is positioned in a cavity 8 formed at the center of the supporting member 6. That is, the supporting member 6 is positioned around the semiconductor chip 2 in a state that the supporting member 6 is arranged on the circuit board 3. It is set so that the height of the supporting member 6 from a mounting face 3a of the circuit board 3 is substantially equal to the height of the semiconductor chip 2 in a state mounted on the circuit board 3. The radiation fin 4 is made of, for example, aluminum and is joined to the supporting member 6 and the semiconductor chip 2 by using an adhesive 10.



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